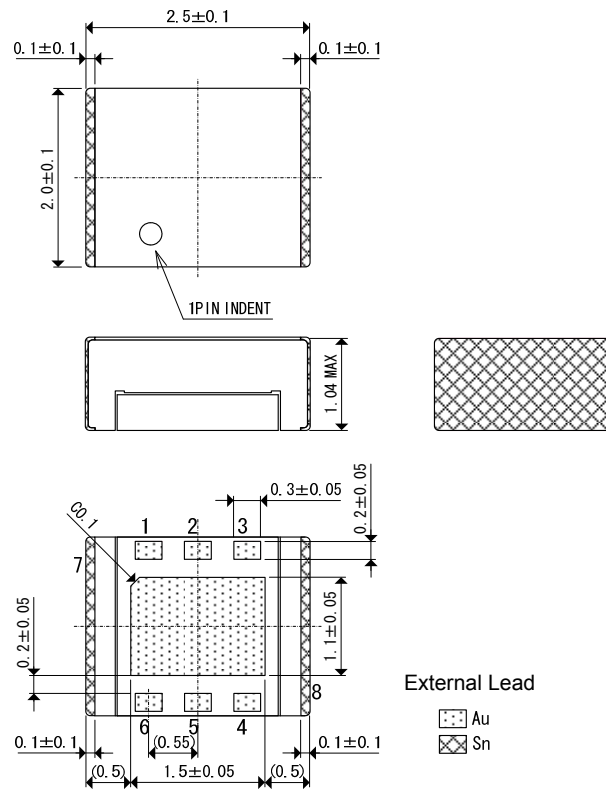


# Packaging Information / Reference Pattern Layout Dimensions

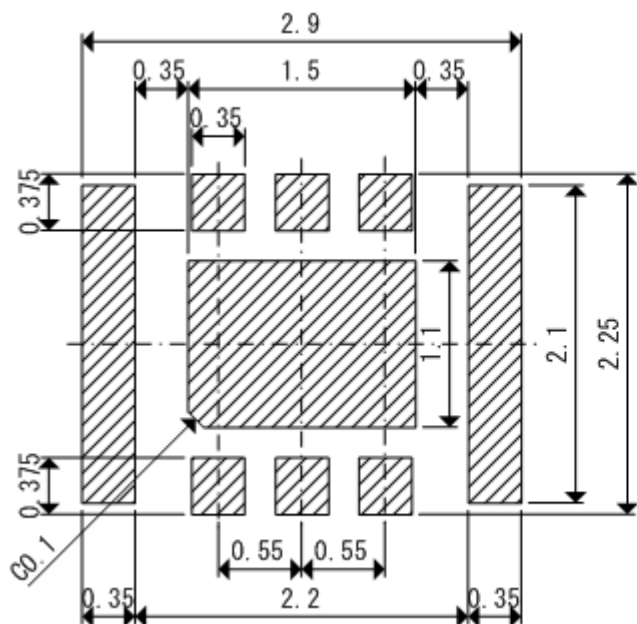
●CL-2025

## ■Packaging Information

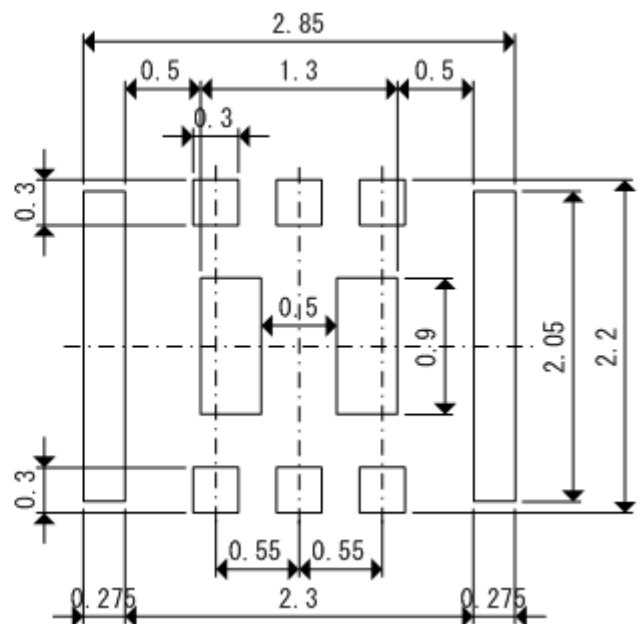
Unit: mm



## ■Reference Pattern Layout Dimension



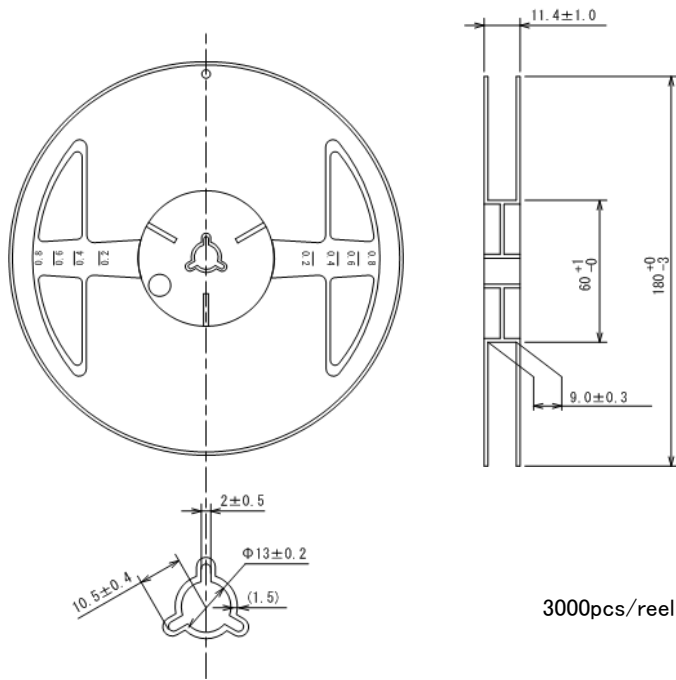
## ■Reference metal mask design



# Taping Specifications

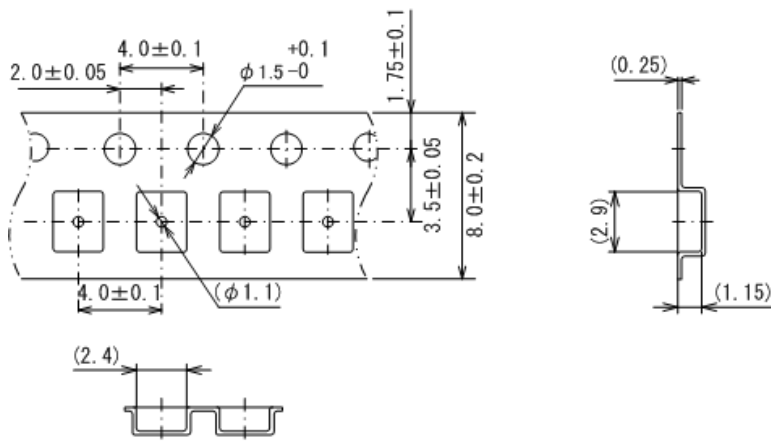
●CL-2025 Reel

Unit: mm

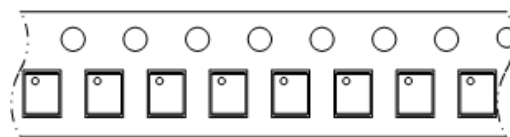


3000pcs/reel

●Taping Specifications



direction of feed



R Type :[Device orientation : Right]

Standard feed

● **CL-2025 Power Dissipation**

Power dissipation data for the CL-2025 is shown in this page.

The value of power dissipation varies with the mount board conditions.

Please use this data as one of reference data taken in the described condition.

1. Measurement Condition (Reference data)

Condition: Mount on a board

Ambient: Natural convection

Soldering: Lead (Pb) free

Board: Dimensions 40 x 40 mm (1600 mm<sup>2</sup> in one side)

Copper (Cu) traces occupy 50% of the board area

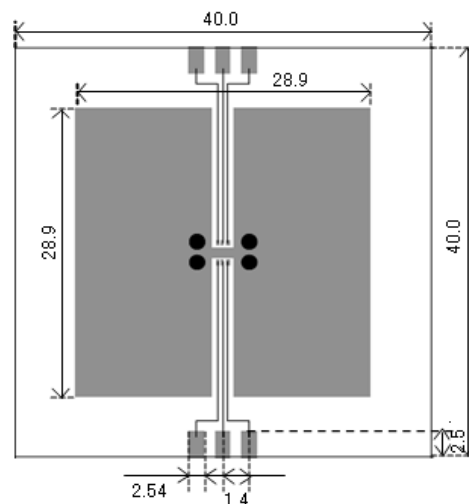
In top and back faces

Package heat-sink is tied to the copper traces

Material: Glass Epoxy (FR-4)

Thickness: 1.6 mm

Through-hole: 4 x 0.8 Diameter

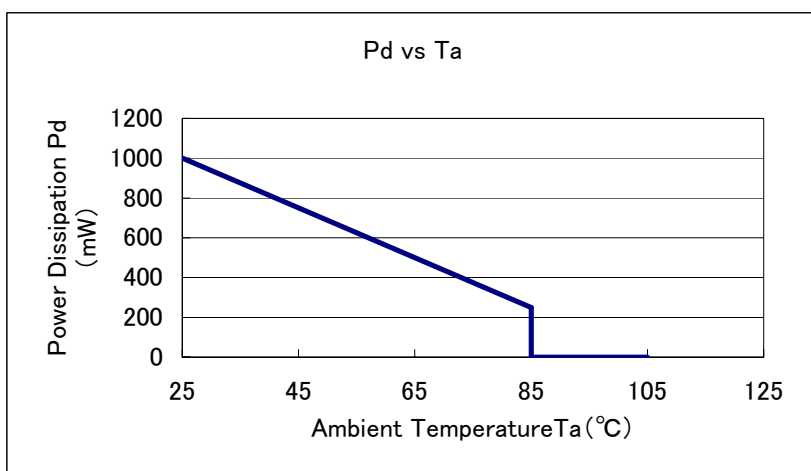


Evaluation Board (Unit: mm)

2. Power Dissipation vs. Ambient Temperature

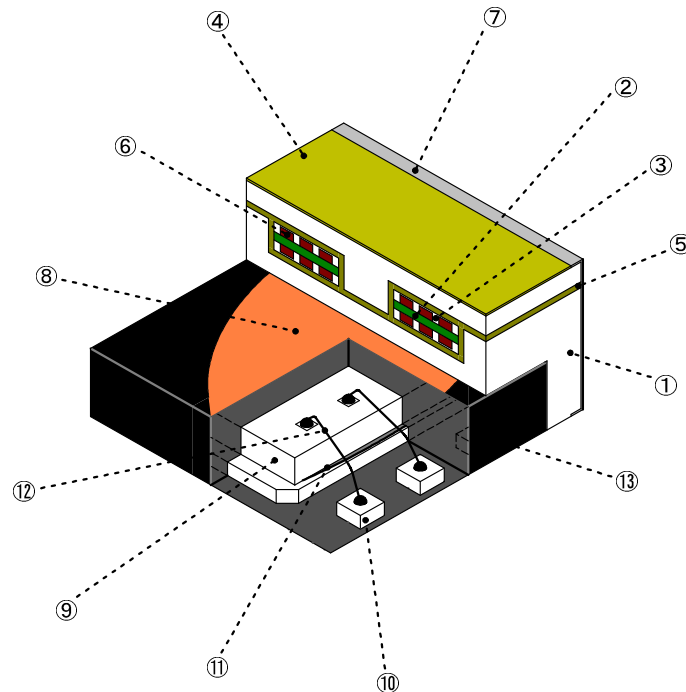
Board Mount ( $T_j \text{ max} = 125^\circ\text{C}$ )

Ambient Temperature ( $^\circ\text{C}$ )	Power Dissipation $P_d$ (mW)	Thermal Resistance ( $^\circ\text{C}/\text{W}$ )
25	1000	100.00
85	250	



CL-2025 構造図  
CL-2025 Perspective

RoHS対応品  
RoHS Compliance



	項目 Item	材料 Material
コイル/Coil	① コア Core	フェライト Ferrite
	② ベース基板 Base Substrate	BTレジン+エポキシ樹脂 BT Resin + Epoxy Resin
	③ 中間保護膜樹脂A Overcoating Resin A	エポキシ樹脂 Epoxy Resin
	④ 保護膜樹脂B (トップコーティング) Overcoating Resin B (Top Coating)	
	⑤ 接着樹脂 Adhesive Resin	
	⑥ 導体(巻線部) Conductor	銅 Copper
	⑦ 端子 Terminal	鉛フリーはんだメッキ, ニッケル Lead(Pb) free solder plating, Nickel
接着剤 Adhesive Resin	⑧ 接着剤 Adhesive Resin	エポキシ樹脂 Epoxy Resin
IC	⑨ シリコンチップ Silicon Chip	シリコン Silicon
	⑩ リードパッド Lead-Pad	ニッケル, 金 Nickel, Gold Plating
	⑪ ダイアタッチ Die Attach	エポキシ Epoxy
	⑫ ボンディングワイヤ Bonding Wire	金 Au
	⑬ 封止樹脂 Resin	エポキシ樹脂 Epoxy Resin
捺印表示 Marking		レーザー Laser Marking